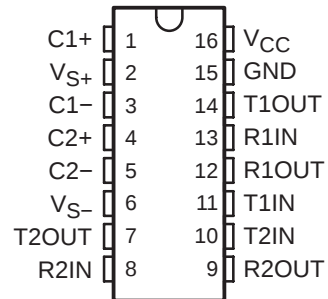


MAX232, MAX232I DUAL EIA-232 DRIVERS/RECEIVERS

SLLS047L – FEBRUARY 1989 – REVISED MARCH 2004

- Meets or Exceeds TIA/EIA-232-F and ITU Recommendation V.28
- Operates From a Single 5-V Power Supply With 1.0- μ F Charge-Pump Capacitors
- Operates Up To 120 kbit/s
- Two Drivers and Two Receivers
- ± 30 -V Input Levels
- Low Supply Current . . . 8 mA Typical
- ESD Protection Exceeds JESD 22 – 2000-V Human-Body Model (A114-A)
- Upgrade With Improved ESD (15-kV HBM) and 0.1- μ F Charge-Pump Capacitors is Available With the MAX202
- Applications
 - TIA/EIA-232-F, Battery-Powered Systems, Terminals, Modems, and Computers

MAX232 . . . D, DW, N, OR NS PACKAGE
MAX232I . . . D, DW, OR N PACKAGE
(TOP VIEW)



description/ordering information

The MAX232 is a dual driver/receiver that includes a capacitive voltage generator to supply TIA/EIA-232-F voltage levels from a single 5-V supply. Each receiver converts TIA/EIA-232-F inputs to 5-V TTL/CMOS levels. These receivers have a typical threshold of 1.3 V, a typical hysteresis of 0.5 V, and can accept ± 30 -V inputs. Each driver converts TTL/CMOS input levels into TIA/EIA-232-F levels. The driver, receiver, and voltage-generator functions are available as cells in the Texas Instruments LinASIC™ library.

ORDERING INFORMATION

T _A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (N)	Tube of 25	MAX232N	MAX232N
	SOIC (D)	Tube of 40	MAX232D	MAX232
		Reel of 2500	MAX232DR	
	SOIC (DW)	Tube of 40	MAX232DW	MAX232
		Reel of 2000	MAX232DWR	
-40°C to 85°C	SOP (NS)	Reel of 2000	MAX232NSR	MAX232
	PDIP (N)	Tube of 25	MAX232IN	MAX232IN
	SOIC (D)	Tube of 40	MAX232ID	MAX232I
		Reel of 2500	MAX232IDR	
	SOIC (DW)	Tube of 40	MAX232IDW	MAX232I
		Reel of 2000	MAX232IDWR	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinASIC is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2004, Texas Instruments Incorporated

MAX232, MAX232I
DUAL EIA-232 DRIVERS/RECEIVERS

SLLS047L – FEBRUARY 1989 – REVISED MARCH 2004

Function Tables

EACH DRIVER

INPUT TIN	OUTPUT TOUT
L	H
H	L

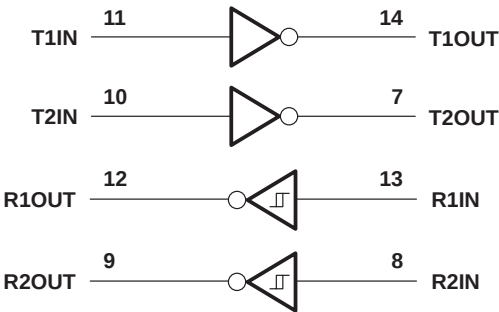
H = high level, L = low level

EACH RECEIVER

INPUT RIN	OUTPUT ROUT
L	H
H	L

H = high level, L = low level

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input supply voltage range, V_{CC} (see Note 1)	–0.3 V to 6 V
Positive output supply voltage range, V_{S+}	$V_{CC} - 0.3$ V to 15 V
Negative output supply voltage range, V_{S-}	–0.3 V to –15 V
Input voltage range, V_I : Driver	–0.3 V to $V_{CC} + 0.3$ V
Receiver	± 30 V
Output voltage range, V_O : T1OUT, T2OUT	$V_{S-} - 0.3$ V to $V_{S+} + 0.3$ V
R1OUT, R2OUT	–0.3 V to $V_{CC} + 0.3$ V
Short-circuit duration: T1OUT, T2OUT	Unlimited
Package thermal impedance, θ_{JA} (see Notes 2 and 3): D package	73°C/W
DW package	57°C/W
N package	67°C/W
NS package	64°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
2. Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage (T1IN, T2IN)	2			V
V_{IL}	Low-level input voltage (T1IN, T2IN)			0.8	V
R1IN, R2IN	Receiver input voltage			± 30	V
T_A	Operating free-air temperature	MAX232	0	70	°C
		MAX232I	–40	85	

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
I_{CC} Supply current	$V_{CC} = 5.5$ V, All outputs open, $T_A = 25^\circ\text{C}$		8	10	mA

[‡] All typical values are at $V_{CC} = 5$ V and $T_A = 25^\circ\text{C}$.

NOTE 4: Test conditions are C1–C4 = 1 μF at $V_{CC} = 5$ V ± 0.5 V.

MAX232, MAX232I

DUAL EIA-232 DRIVERS/RECEIVERS

SLLS047L – FEBRUARY 1989 – REVISED MARCH 2004

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature range (see Note 4)

PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{OH}	High-level output voltage	T1OUT, T2OUT R _L = 3 kΩ to GND	5	7		V
V _{OL}	Low-level output voltage [‡]	T1OUT, T2OUT R _L = 3 kΩ to GND		–7	–5	V
r _o	Output resistance	T1OUT, T2OUT V _{S+} = V _{S–} = 0, V _O = ±2 V	300			Ω
I _{OS} [§]	Short-circuit output current	T1OUT, T2OUT V _{CC} = 5.5 V, V _O = 0		±10		mA
I _{IS}	Short-circuit input current	T1IN, T2IN V _I = 0			200	μA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] The algebraic convention, in which the least-positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels only.

[§] Not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Note 4)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR	Driver slew rate	R _L = 3 kΩ to 7 kΩ, See Figure 2			30	V/μs
SR(t)	Driver transition region slew rate	See Figure 3		3		V/μs
	Data rate	One TOUT switching		120		kbit/s

NOTE 4: Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature range (see Note 4)

PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{OH}	High-level output voltage	R1OUT, R2OUT I _{OH} = –1 mA	3.5			V
V _{OL}	Low-level output voltage [‡]	R1OUT, R2OUT I _{OL} = 3.2 mA			0.4	V
V _{IT+}	Receiver positive-going input threshold voltage	R1IN, R2IN V _{CC} = 5 V, T _A = 25°C		1.7	2.4	V
V _{IT–}	Receiver negative-going input threshold voltage	R1IN, R2IN V _{CC} = 5 V, T _A = 25°C	0.8	1.2		V
V _{hys}	Input hysteresis voltage	R1IN, R2IN V _{CC} = 5 V	0.2	0.5	1	V
r _i	Receiver input resistance	R1IN, R2IN V _{CC} = 5, T _A = 25°C	3	5	7	kΩ

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] The algebraic convention, in which the least-positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels only.

NOTE 4: Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.

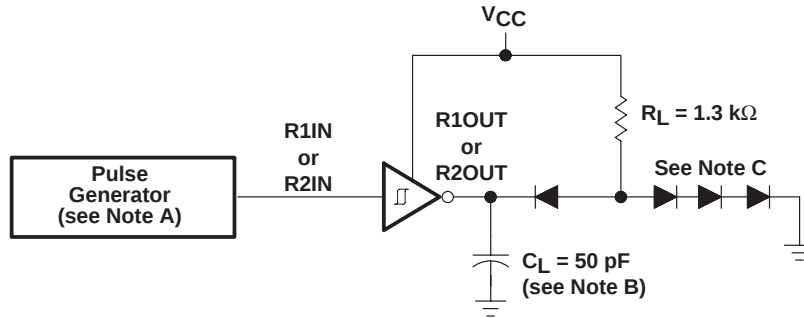
switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Note 4 and Figure 1)

PARAMETER		TYP	UNIT
t _{PLH(R)}	Receiver propagation delay time, low- to high-level output	500	ns
t _{PHL(R)}	Receiver propagation delay time, high- to low-level output	500	ns

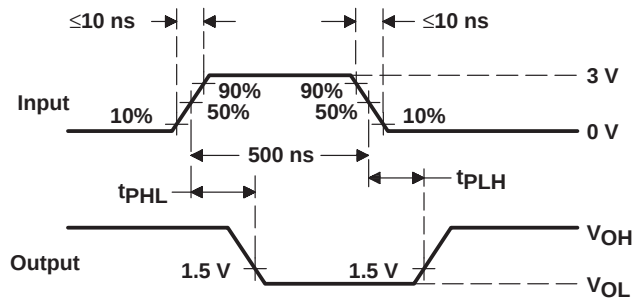
NOTE 4: Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.



PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



WAVEFORMS

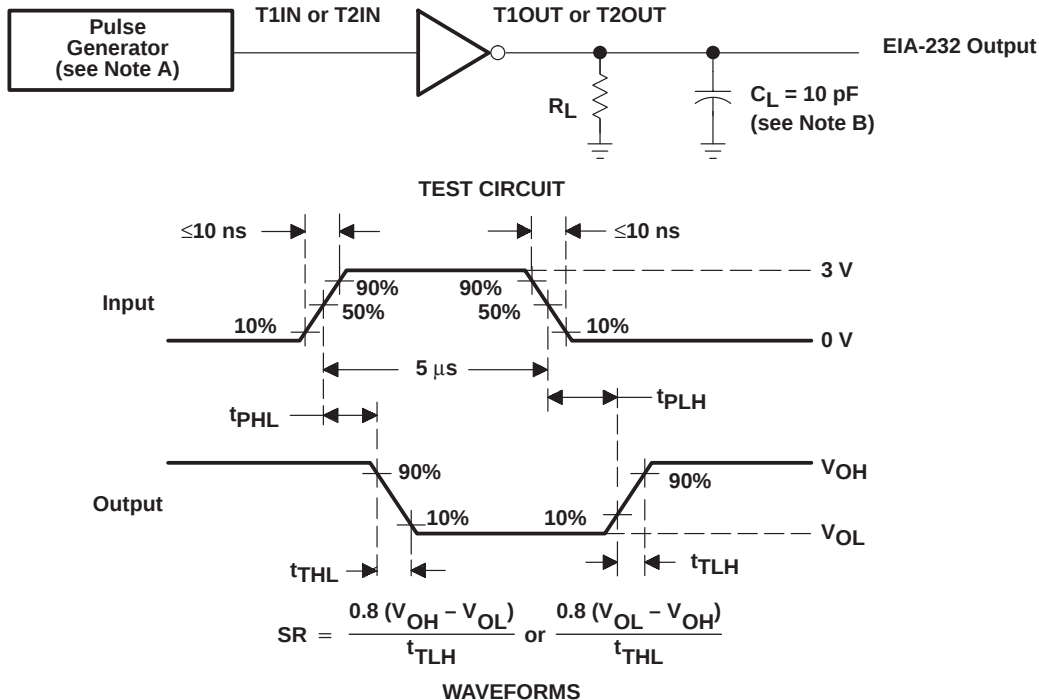
- NOTES: A. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, duty cycle $\leq 50\%$.
B. C_L includes probe and jig capacitance.
C. All diodes are 1N3064 or equivalent.

Figure 1. Receiver Test Circuit and Waveforms for t_{PHL} and t_{PLH} Measurements

MAX232, MAX232I DUAL EIA-232 DRIVERS/RECEIVERS

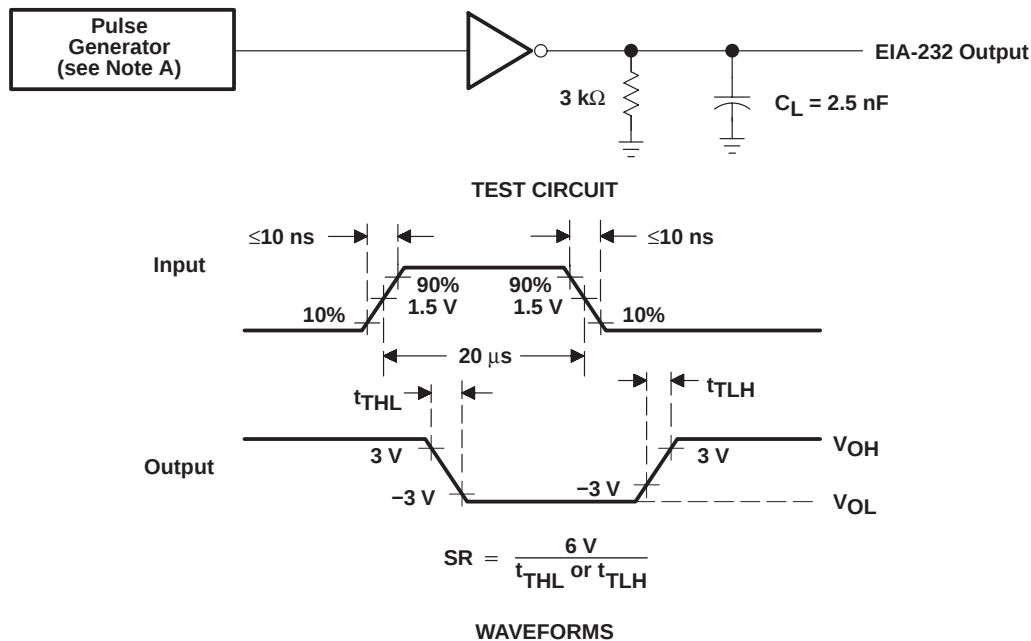
SLLS047L – FEBRUARY 1989 – REVISED MARCH 2004

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, duty cycle $\leq 50\%$.
B. C_L includes probe and jig capacitance.

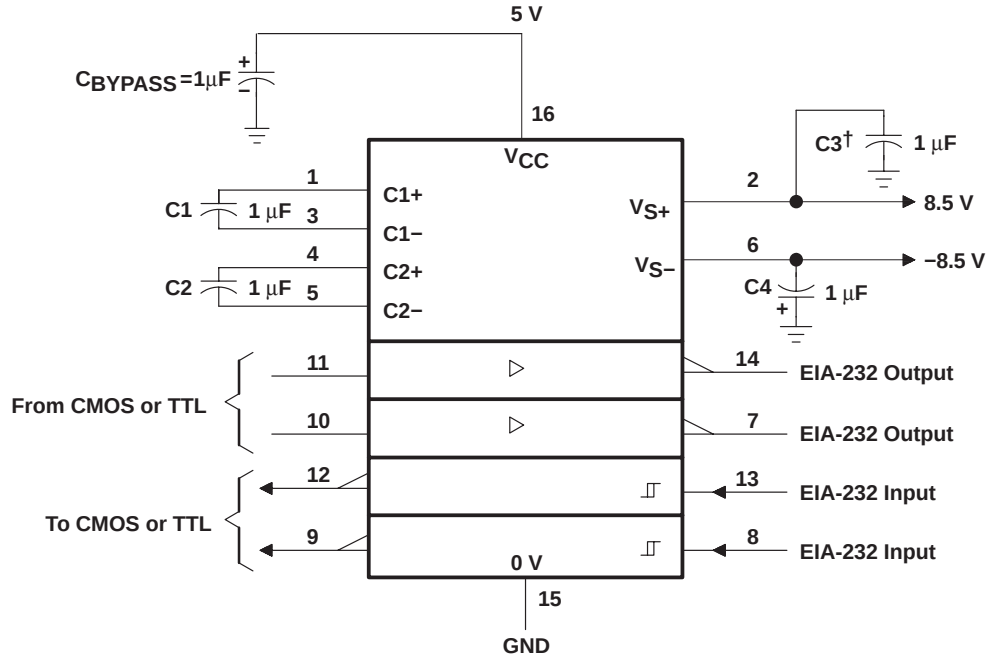
Figure 2. Driver Test Circuit and Waveforms for t_{PHL} and t_{PLH} Measurements (5- μs Input)



NOTE A: The pulse generator has the following characteristics: $Z_O = 50 \Omega$, duty cycle $\leq 50\%$.

Figure 3. Test Circuit and Waveforms for t_{THL} and t_{TLH} Measurements (20- μs Input)

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown. In addition to the 1- μ F capacitors shown, the MAX202 can operate with 0.1- μ F capacitors.

Figure 4. Typical Operating Circuit

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MAX232D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DWE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DWRE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232DWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDWE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDWRE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IDWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MAX232INE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MAX232N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MAX232NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MAX232NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

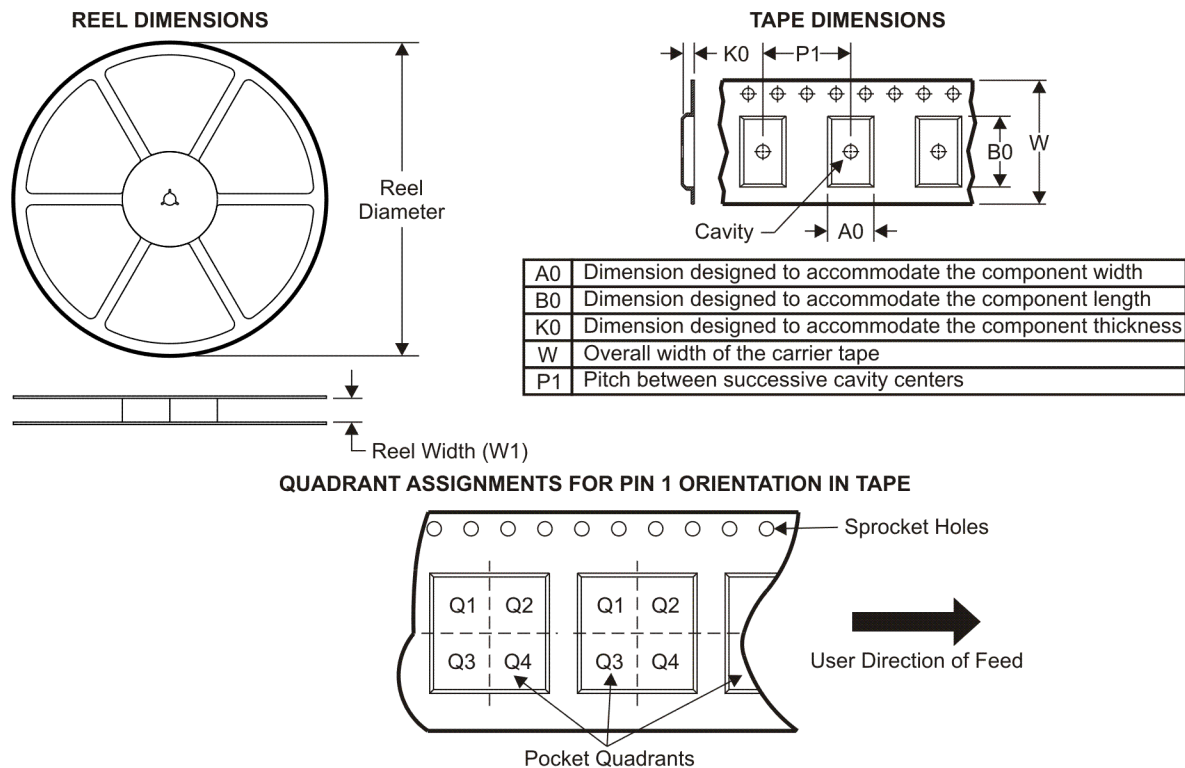
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

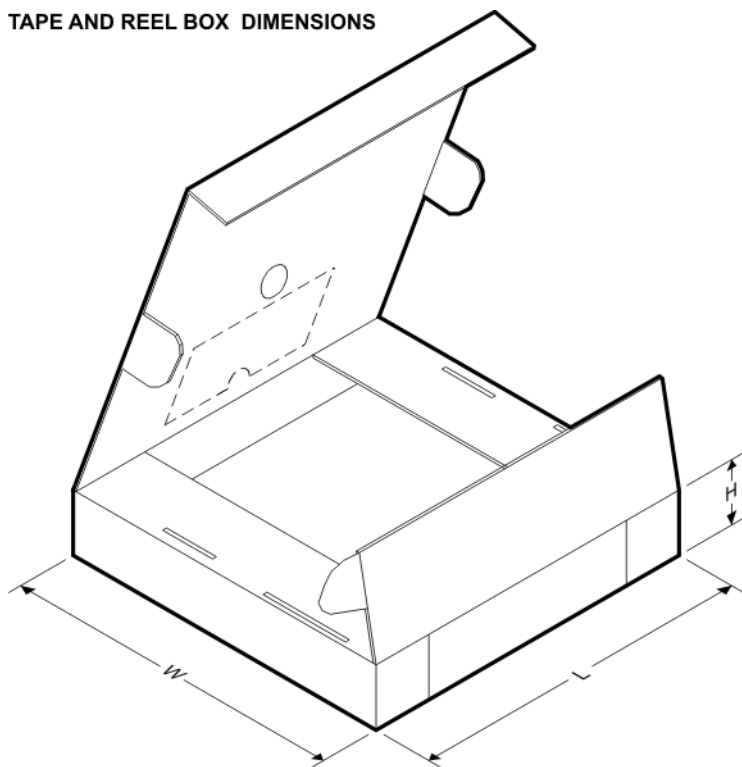
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX232DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
MAX232DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
MAX232DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
MAX232IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
MAX232IDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
MAX232NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



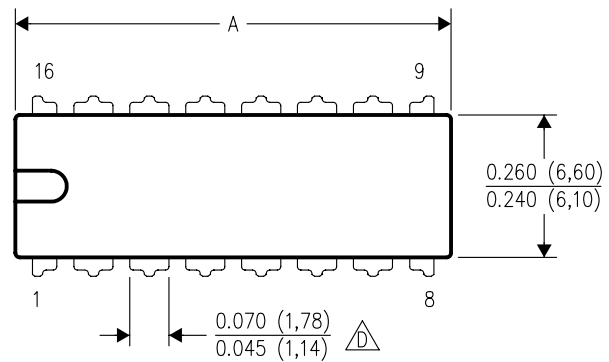
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX232DR	SOIC	D	16	2500	346.0	346.0	33.0
MAX232DR	SOIC	D	16	2500	333.2	345.9	28.6
MAX232DWR	SOIC	DW	16	2000	346.0	346.0	33.0
MAX232IDR	SOIC	D	16	2500	333.2	345.9	28.6
MAX232IDWR	SOIC	DW	16	2000	346.0	346.0	33.0
MAX232NSR	SO	NS	16	2000	346.0	346.0	33.0

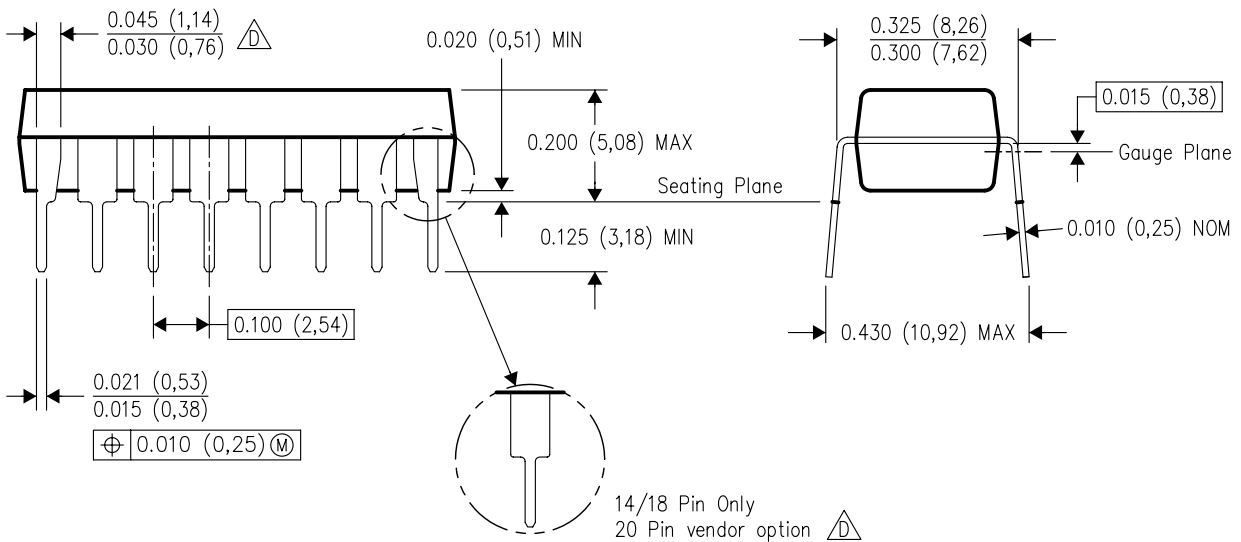
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

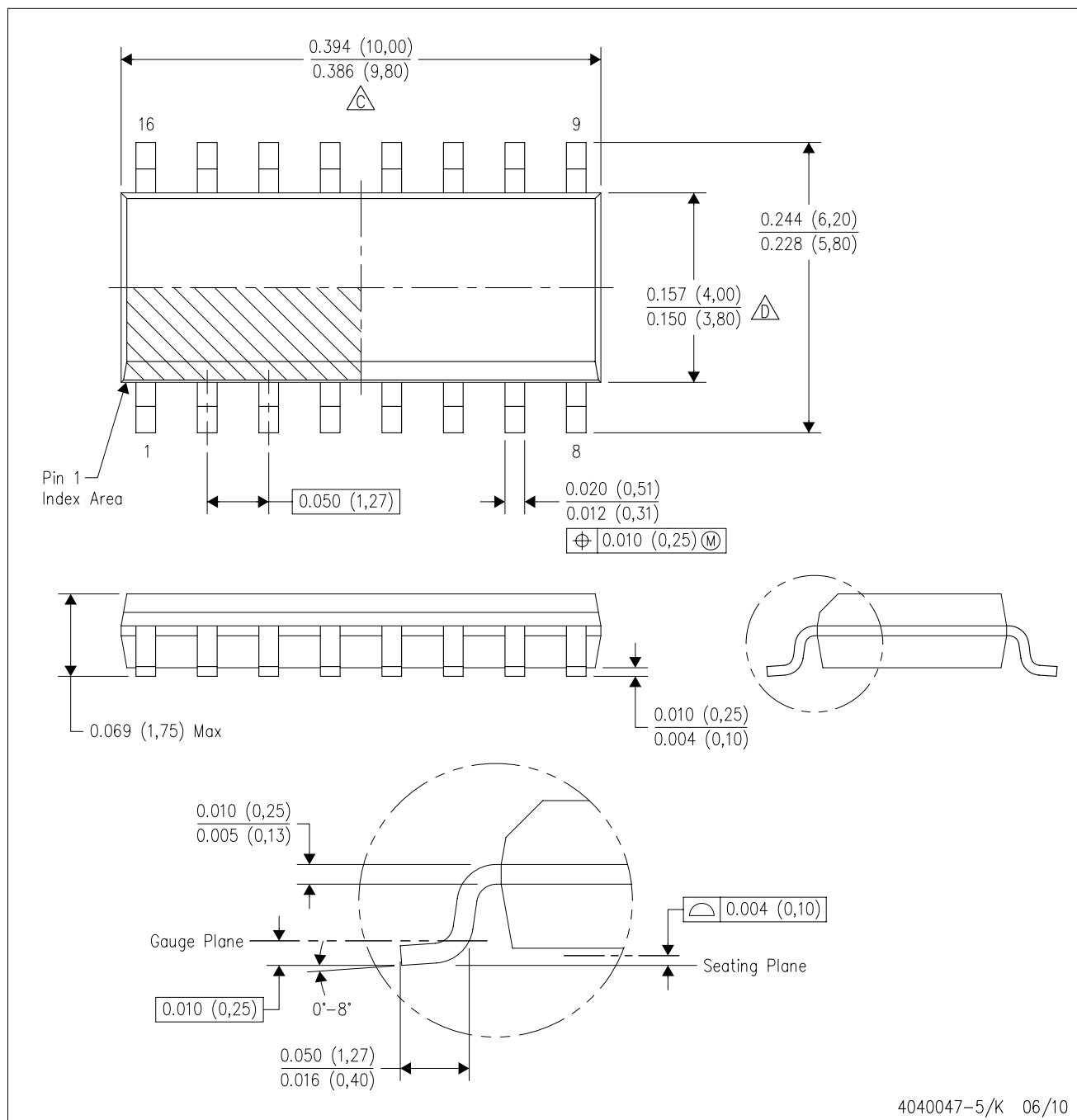


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

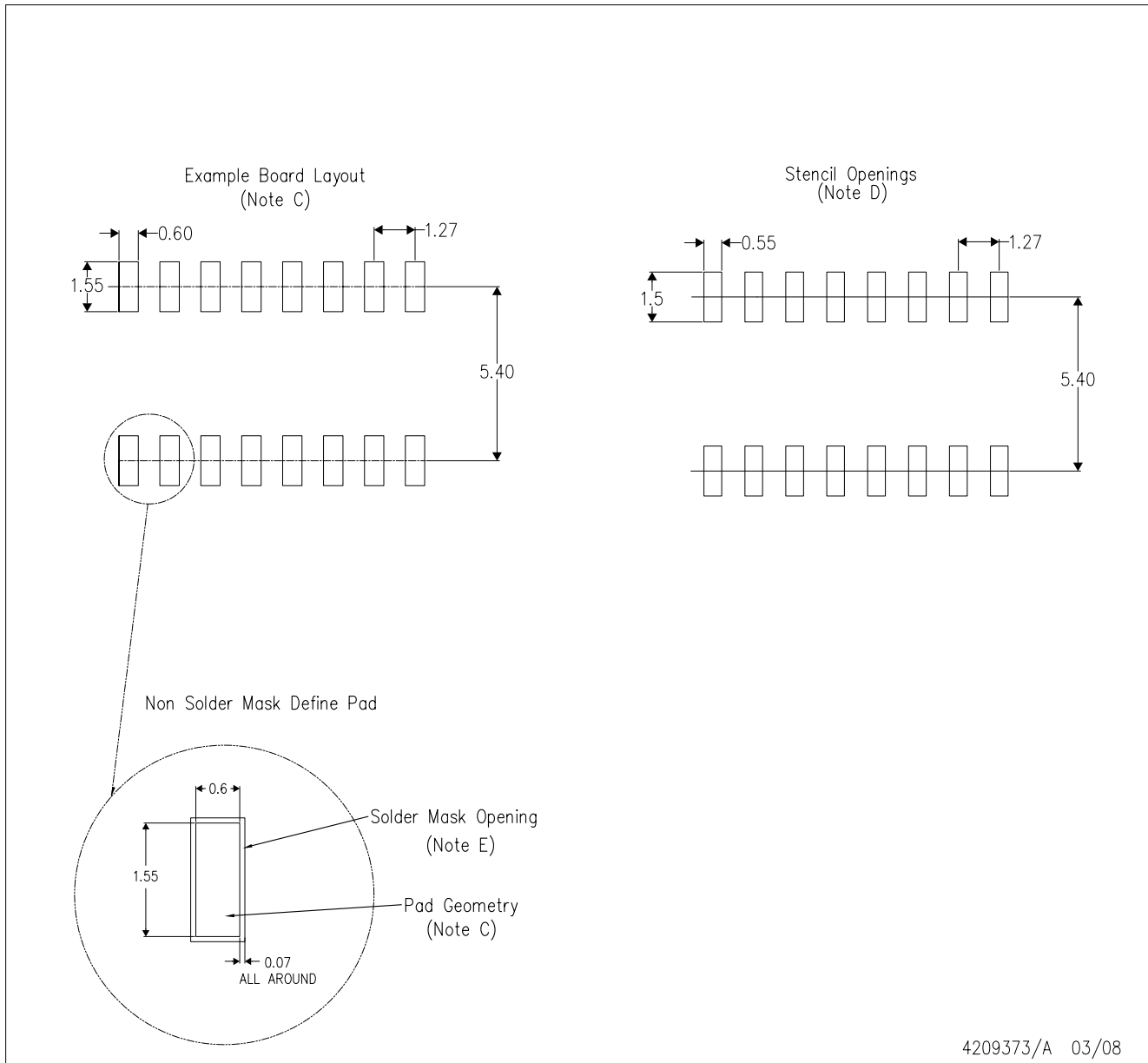
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.

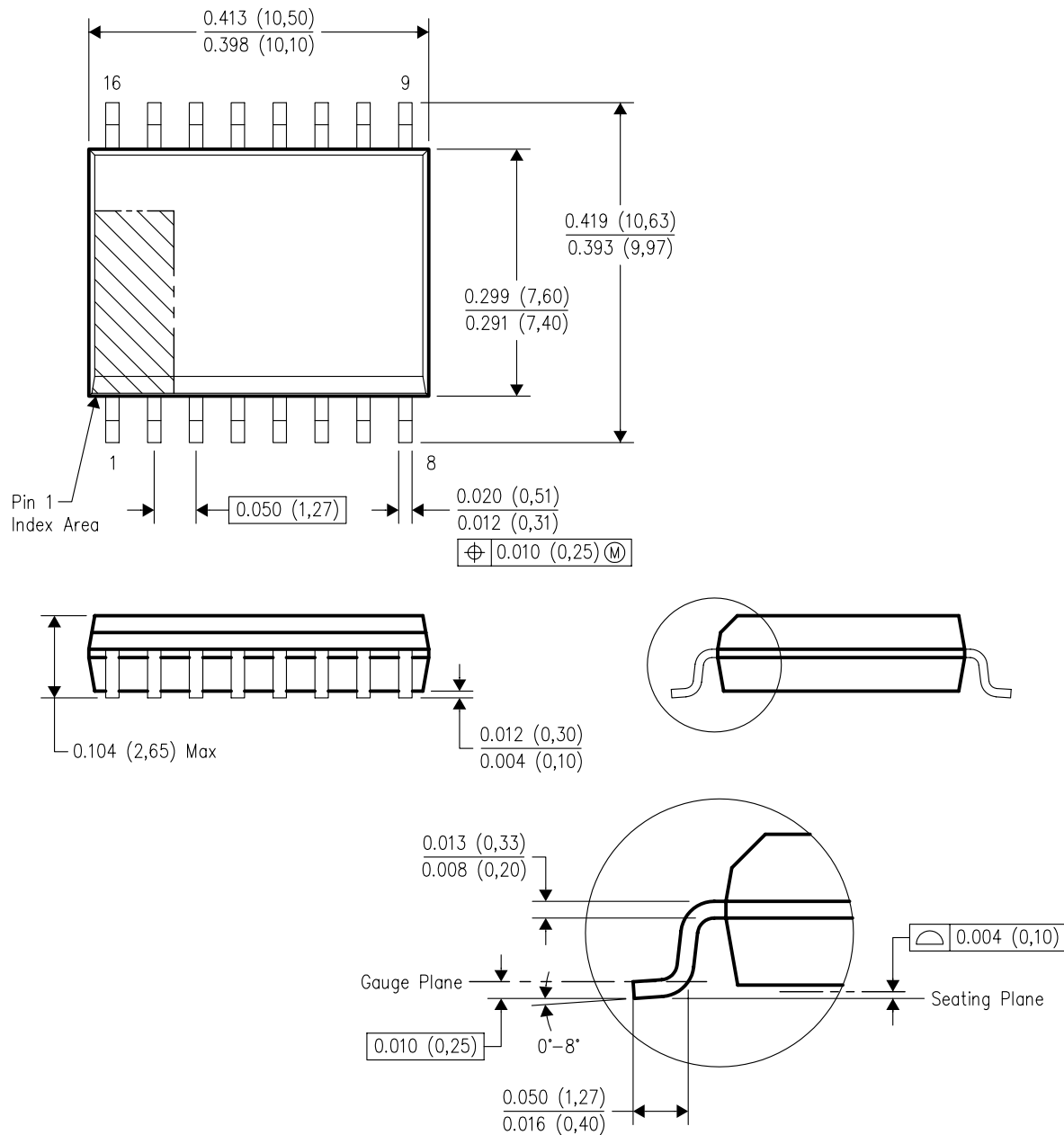
D(R-PDSO-G16)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040000-2/F 06/2004

- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013 variation AA.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics & Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video
Wireless	www.ti.com/wireless-apps



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.